Renesas Electronics America Inc - IDT79RC64V474-200DZ Datasheet

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Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	MIPS-I
Number of Cores/Bus Width	1 Core, 64-Bit
Speed	200MHz
Co-Processors/DSP	System Control; CP0
RAM Controllers	SDRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	0°C ~ 85°C (TC)
Security Features	-
Package / Case	128-BQFP Exposed Pad
Supplier Device Package	128-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/idt79rc64v474-200dz

A secure user processing environment is provided through the **user, supervisor, and kernel operating modes** of virtual addressing to system software. Bits in a status register determine which of these modes is used.

If configured for 64-bit **virtual addressing**, the virtual address space layout becomes an upwardly compatible extension of the 32-bit virtual address space layout. Figure 1 is an illustration of the address space layout for the 32-bit virtual address operation.

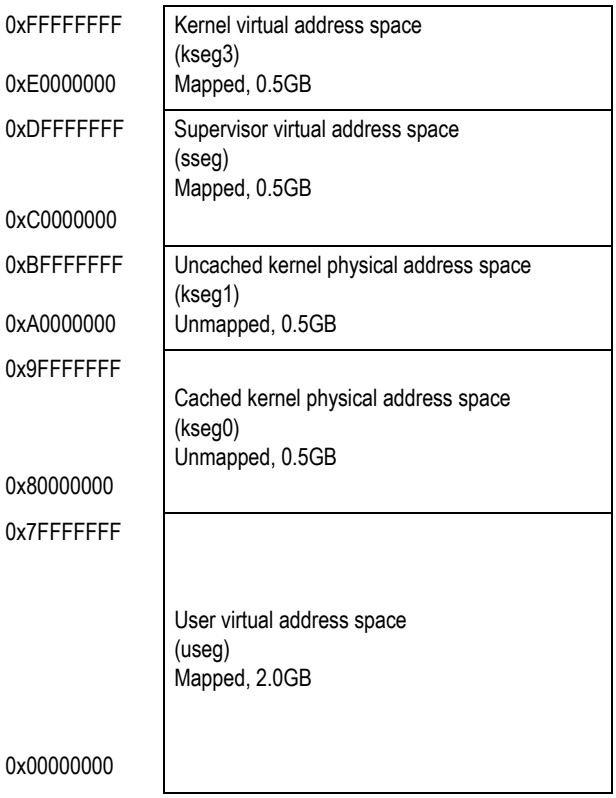


Figure 1 Kernel Mode Virtual Addressing (32-bit Mode)

The RC64474/RC64475's **Memory Management Unit (MMU)** controls the virtual memory system's page mapping and consists of a translation lookaside buffer (TLB) used for the virtual memory-mapping subsystem.

This large, **fully associative TLB** maps 96 virtual pages to their corresponding physical addresses. The TLB is organized as 48 pairs of even-odd entries and maps a virtual address and address space identifier into the large, 64GB physical address space. To assist in controlling the amount of mapped space and the replacement characteristics of various memory regions, two mechanisms are provided. First, the page size can be configured on a **per-entry basis**, to map a page size of 4KB to 16MB (in increments of 4x).

The second mechanism controls the replacement algorithm, when a TLB miss occurs. A random replacement algorithm is provided to select a TLB entry to be written with a new mapping; however, the processor provides a mechanism whereby a system specific number of mappings can be locked into the TLB and avoid being randomly replaced, which facilitates the design of real-time systems, by allowing deterministic access to critical software.

The TLB also contains information to control the cache coherency protocol, and cache management algorithm for each page. However, hardware-based cache coherency is not supported.

The RC64474 and RC64475 enhance IDT's entire RISCore4000 series through the implementation of features such as boundary scan, to facilitate board level testing; enhanced support for SyncDRAM, to simplify system implementation and improve performance.

The RC64474/475 processors offer a **direct migration path** for designs based on IDT's RC4640/RC4650 processors[2], through full pin and socket compatibility. Also, full 64-bit-family software and bus-protocol compatibility ensures the RC64474/475 access to a robust development tools infrastructure, allowing quicker time to market.

Development Tools

An array of hardware and software tools is available to assist system designers in the rapid development of RC64474/475 based systems. This accessibility allows a wide variety of customers to take full advantage of the device's high-performance features while addressing today's aggressive time-to-market demands.

Cache Memory

To keep the RC64474 and RC64475's high-performance pipeline full and operating efficiently, on-chip instruction and data caches have been incorporated. Each cache has its own data path and can be accessed in the same single pipeline clock cycle.

The 16KB two-way set associative **instruction cache (I-cache)** is virtually indexed, physically tagged, and word parity protected. Because this cache is virtually indexed, the virtual-to-physical address translation occurs in parallel with the cache access, further increasing performance by allowing both operations to occur simultaneously. The instruction cache provides a peak instruction bandwidth of 1000MB/sec at 250MHz.

The 16KB two-way set associative **data cache (D-cache)** is byte parity protected and has a fixed 32-byte (eight words) line size. Its tag is protected with a single parity bit. To allow simultaneous address translation and data cache access, the D-cache is virtually indexed and physically tagged. The data cache can provide 8 bytes each clock cycle, for a peak bandwidth of 2GB/sec.

To lock critical sections of code and/or data into the caches for quick access, a **"cache locking"** feature has been implemented. Once enabled, a cache is said to be locked when a particular piece of code or data is loaded into the cache and that cache location will not be selected later for refill by other data. This feature locks a set (8KB) of Instructions and/or Data.

Table 2 lists the RC64474/475 Instruction and data cache attributes.

[2] To ensure socket compatibility, refer to Table 8 and Table 9 at back of data sheet.

Characteristics	Instruction	Data
Size	16KB	16KB
Organization	2-way set associative	2-way set associative
Line size	32B	32B
read unit	32-bits	64-bits
write policy	na	write-back, write-through with or without write-allocate
Line transfer order	sub-block order, for refill	sub-block order, for load sequential order, for store
Miss restart after transfer of:	entire line	miss word
Parity	per-word	per-byte
Cache locking	per set	per set

Table 2 RC64474/RC64475 Instruction/Data Cache Attributes

System Interfaces

The RC64475 supports a 64-bit system interface that is bus compatible with the RC4650 and RC64575 system interface. The system interface consists of a 64-bit Address/Data bus with 8 check bits and a 9-bit command bus that is parity protected.

During 64-bit operation, RC64475 system address/data (SysAD) transfers are protected with an 8-bit parity check bus, SysADC. When initialized for 32-bit operation, the RC64475's SysAD can be viewed as a 32-bit multiplexed bus that is protected by 4 parity check bits.

The RC64474 supports a 32-bit system interface that is bus compatible with the RC4640. During 32-bit operation, SysAD transfers are performed on a 32-bit multiplexed bus (SysAD 31:0) that is protected by 4 parity check bits (SysADC 6:0).

Writes to external memory—whether they are cache miss write-backs, stores to uncached or write-through addresses—use the on-chip **write buffer**. The write buffer holds a maximum of four 64-bit addresses and 64-bit data pairs. The entire buffer is used for a data cache write-back and allows the processor to proceed in parallel with memory updates.

Included in the system interface are **six handshake signals**: RdRdy*, WrRdy*, ExtRqst*, Release*, ValidOut*, and ValidIn*; **six interrupt inputs,** and a **simple timing** specification that is capable of transferring data between the processor and memory at a peak rate of 1000MB/sec. A boot-time selectable option to run the system interface as 32-bits wide—using basically the same protocols as the 64-bit system—is also supported.

A **boot-time mode control interface** initializes fundamental processor modes. The boot-time mode control interface is a serial interface that operates at a very low frequency (MasterClock divided by 256). This low-frequency operation allows the initialization information to be kept in a low-cost EPROM; alternatively, the twenty-or-so bits could be generated by the system interface ASIC or a simple PAL. The boot-time serial stream and configuration options are listed in Table 3.

The **clocking interface** allows the CPU to be easily mated with external reference clocks. The CPU input clock is the bus reference clock and can be between 25 and 125MHz. An on-chip **phase-locked-loop (PLL)** generates the pipeline clock (PClock) through multiplication of the system interface clock by values of 2,3,4,5,6,7 or 8, as defined at system reset. This allows the pipeline clock to be implemented at a significantly higher frequency than the system interface clock. The RC64474/475 support single data (one to eight bytes) and 8-word block transfers on the SysAD bus.

The RC64474/475 implement additional **write protocols** that **double the effective write bandwidth**. The write re-issue has a repeat rate of 2 cycles per write. Pipelined writes have the same 2-cycle per write repeat rate, but can issue an additional write after WrRdy* de-asserts.

Choosing a 32- or 64-bit wide system interface dictates whether a cache line block transaction requires 4 double word data cycles or 8 single word cycles as well as whether a single data transfer—larger than 4 bytes—must be divided into two smaller transfers.

Board-level testing during Run-Time mode is facilitated through the full JTAG boundary scan facility. Six pins—TDI, TDO, TMS, TCK, TRST* and JTAG32*—have been incorporated to support the standard JTAG interface.

System Enhancement

To facilitate discrete **interface to SDRAM**, the RC64474/475 bus interface is enhanced during write cycles with a programmable delay that is inserted between the write address and the write data (for both block and non-block writes).

The bus delay can be defined as 0 to 7 MasterClock cycles and is activated and controlled through mode bit (17:15) settings selected during the reset initialization sequence. The '000' setting provides the same write operations timing protocol as the RC4640, RC4650, and RC5000 processors.

Serial Bit	Description	Value & Mode Setting	
255:18	Reserved	Must be 0	
17:15	WAdrWData_Del Write address to write data delay in Master-Clock cycles.®	000 → 0 cycles 001 → 1 cycle 010 → 2 cycles 011 → 3 cycles 100 → 4 cycles 101 → 5 cycles 110 → 6 cycles 111 → 7 cycles	
14:13	Drv_Out output driver slew rate control. **Bit 14 is MSB.** Affects only non-clock outputs.	Output driver strength: 10 → 100% strength (fastest) 11 → 83% strength 00 → 67% strength 01 → 50% strength (slowest)	
12	System interface bus width	0 → 64-bit system interface 1 → 32-bit system interface	
11	TmrIntEn Disables the timer interrupt on Int*[5]	0 → Enabled Timer Interrupt 1 → Disabled Timer Interrupt	
10:9	Non-block write Selects non-block write type. **Bit 10 is MSB.**	00 → RC4x00 compatible 01 → Reserved 10 → Pipelined writes 11 → Write re-issue	
7:5	Clock Multiplier MasterClock is multiplied internally to generate PClock	Clock multiplier: 0 Multiply by 2 1 Multiply by 3 2 Multiply by 4 3 Multiply by 5 4 Multiply by 6 5 Multiply by 7 6 Multiply by 8 7 Reserved	
8	EndBit Specifies byte ordering	0 → Little endian 1 → Big endian	
4:1	Writeback data rate System interface data rate for block writes only: **bit 4 is MSB**	64-bit: 9:15 Reserved 8 → dxxxdxxxdxxxdxxx 7 → ddxxxxxxddxxxxxx 6 → dxxdxxdxxdxx 5 → ddxxxxddxxxx 4 → ddxxxddxxx 3 → dxdxdxdx 2 → ddxxddxx 1 → ddxddx 0 → dddd	32-bit: 9:15 Reserved 8 → wxxxwxxxwxxxwxxxwxxxwxxxwxxxwxxx 7 → wwxxxxxxwwxxxxxxwwxxxxxxwwxxxxxx 6 → wxxwxxwxxwxxwxxwxxwxxwxx 5 → wwxxxxwwxxxxwwxxxxwwxxxx 4 → wwxxxwwxxxwwxxxwwxxx 3 → wxwxwxwxwxwxwxwx 2 → wwxxwwxxwwxxwwxx 1 → wwxwwxwwxwwx 0 →Æ wwwwwwww
0	Reserved	Must be zero	

Table 3 Boot-time Mode Stream

Power Management

Executing the WAIT instruction enables the processor to enter Standby mode. The internal clocks will shut down, thus freezing the pipeline. The PLL, internal timer, and some of the input pins (Int[5:0]*, NMI*, ExtReq*, Reset*, and ColdReset*) will continue to run. Once the CPU is in Standby Mode, any interrupt, including the internally generated timer interrupt, will cause the CPU to exit Standby Mode.

Thermal Considerations

The RC64474/475 come in a QFP with a drop-in heat spreader and are guaranteed in a case temperature range of 0° to +85° C, for commercial temperature devices; - 40° to +85° for industrial temperature devices. The type of package, speed (power) of the device, and airflow conditions affect the equivalent ambient temperature conditions that will meet this specification.

The equivalent allowable ambient temperature, T_A, can be calculated using the thermal resistance from case to ambient ($\varnothing_{CA}$) of the given package. The following equation relates ambient and case temperatures:

$T_A = T_C - P * \varnothing_{CA}$

where P is the maximum power consumption at hot temperature, calculated by using the maximum I_{CC} specification for the device.

Typical values for $\varnothing_{CA}$ at various airflows are shown in Table 4. Note that the RC64474/475 processors implement advanced power management, which substantially reduces the typical power dissipation of the device.

	∅CA					
Airflow (ft/min)	**0**	**200**	**400**	**600**	**800**	**1000**
128 QFP	16	10	9	7	6	5
208 QFP	20	13	10	9	8	7

Table 4 Thermal Resistance (∅CA) at Various Airflows

Data Sheet Revision History

December 1998: Changed ordering code on 128-pin package from DQ / DQI (Industrial) to DZ / DZI (Industrial).

January 1999: Removed 5V tolerance capability and deleted 5V tolerant pin.

February 1999: Changed the package drawings to reflect the new 208-pin DP (DPI) and 128-pin DZ (DZI) packages.

May 1999: Removed "Preliminary" status from data sheet.

Changes in DC Electrical Characteristics table. Changes in Pin Description table. Changes in Clock Parameters table. Changes in System Interface Parameters table.

September 1999: Updated Revision History section.

January 17, 2000: Added "with DSP extensions" in the CPU row under RC64574 and RC64575 columns in Table 1. Added "lockable by line" in the Caches row under RC64574 and RC64575 columns in Table 1. Revised Data Output and Data Output Hold rows in System Interface Parameters table.

February 10, 2000: Revised values in Table 4, Thermal Resistance.

Old values were:

	∅CA					
Airflow (ft/min)	**0**	**200**	**400**	**600**	**800**	**1000**
128 QFP	20	12	9	8	7	6
208 QFP	20	12	9	8	7	6

March 13, 2000: Replaced existing figure in Mode Configuration Interface Reset Sequence section with 3 reset figures.

March 28, 2000: Removed the symbol t_{DZ} from Figure 3.

April 17, 2000: Changed V_{IH} value in 200MHz column from 2.0V to $0.7V_{CC}$.

April 10, 2001: In the Data Output and Data Output Hold categories of the System Interface Parameters table, changed values in the Min column for all speeds from 1.0 to 0. Deleted Output for Loading AC Testing diagram and added Output Loading for AC Timing diagram (Figure 8).

Pin Description Table

The following is a list of system interface pins available on the RC64474/475. Pin names ending with an asterisk (*) are active when low.

Pin Name	Type	Description
System Interface		
ExtRqst*	I	**External request** An external agent asserts ExtRqst* to request use of the System interface. The processor grants the request by asserting Release*.
Release*	O	**Release interface** In response to the assertion of ExtRqst* or a CPU read request, the processor asserts Release* and signals to the requesting device that the system interface is available.
RdRdy*	I	**Read Ready** The external agent asserts RdRdy* to indicate that it can accept a processor read request.
WrRdy*	I	**Write Ready** An external agent asserts WrRdy* when it can now accept a processor write request.
ValidIn*	I	**Valid Input** Signals that an external agent is now driving a valid address or data on the SysAD bus and a valid command or data identifier on the SysCmd bus.
ValidOut*	O	**Valid output** Signals that the processor is now driving a valid address or data on the SysAD bus and a valid command or data identifier on the SysCmd bus.
SysAD(63:0)	I/O	**System address/data bus** A 64-bit address and data bus for communication between the processor and an external agent. During address phases only, SysAd(35:0) contains valid address information. The remaining SysAD(63:36) pins are not used. The whole 64-bit SysAD(63:0) may be used during the data transfer phase. In 32-bit mode and in the RC64474, SysAD(63:32) is not used, regardless of Endianness. A 32-bit address and data communication between processor and external agent is performed via SysAD(31:0).
SysADC(7:0)	I/O	**System address/data check bus** An 8-bit bus containing parity check bits for the SysAD bus during data bus cycles. In 32-bit mode and in the RC64474, SysADC(7:4) is not used. The SysADC(3:0) contains check bits for SysAD(31:0).
SysCmd(8:0)	I/O	**System command/data identifier bus** A 9-bit bus for command and data identifier transmission between the processor and an external agent.
SysCmdP	I/O	System Command Parity A single, even-parity bit for the Syscmd bus. This signal is always driven low.
Clock/Control Interface		
MasterClock	I	**Master Clock** Master clock input establishes the processor and bus operating frequency. It is multiplied internally by 2,3,4,5,6,7,8 to generate the pipeline clock (PClock). This clock must be driven by 3.3V (Vcc) clock signals, regardless of the 5V tolerant pin setting.
VccP	I	Quiet VCC for PLL Quiet Vcc for the internal phase locked loop.
VssP	I	**Quiet Vss for PLL** Quiet Vss for the internal phase locked loop.
Interrupt Interface		
Int*(5:0)	I	**Interrupt** Six general processor interrupts, bit-wise ORed with bits 5:0 of the interrupt register.

Table 5 Pin Descriptions (Page 1 of 2)

Pin Name	Type	Description
NMI*	I	**Non-maskable interrupt** Non-maskable interrupt, ORed with bit 6 of the interrupt register.
Initialization Interface		
V_{CC}Ok	I	**V_{CC} is OK** When asserted, this signal indicates to the processor that the power supply has been above the Vcc minimum for more than 100 milliseconds and will remain stable. The assertion of VCCOk initiates the initialization sequence.
ColdReset*	I	**Cold reset** This signal must be asserted for a power on reset or a cold reset. ColdReset must be de-asserted synchronously with MasterClock.
Reset*	I	**Reset** This signal must be asserted for any reset sequence. It can be asserted synchronously or asynchronously for a cold reset, or synchronously to initiate a warm reset. Reset must be de-asserted synchronously with MasterClock.
ModeClock	O	**Boot-mode clock** Serial boot-mode data clock output at the system clock frequency divided by two hundred fifty-six.
ModeIn	I	**Boot-mode data in** Serial boot-mode data input.
JTAG Interface		
TDI	I	JTAG Data In On the rising edge of TCK, serial input data are shifted into either the Instruction register or Data register, depending on the TAP controller state.
TDO	O	JTAG Data Out On the falling edge of TCK, the TDO is serial data shifted out from either the instruction or data register. When no data is shifted out, the TDO is tri-stated (high impedance).
TCK	I	JTAG Clock Input An input test clock used to shift into or out of the boundary-scan register cells. TCK is independent of the system and processor clock with nominal 40-60% duty cycle.
TMS	I	JTAG Command Select The logic signal received at the TMS input is decoded by the TAP controller to control test operation. TMS is sampled on the rising edge of TCK.
TRST*	I	JTAG Reset The TRST* pin is an active-low signal used for asynchronous reset of the debug unit, independent of the processor logic. During normal CPU operation, the JTAG controller will be held in the reset mode, asserting this active low pin. When asserted low, this pin will also tristate the TDO pin.
JTAG32*	I	JTAG 32-bit scan This pin is used to control length of the scan chain for SYsAD (32-bit or 64-bit) for the JTAG mode. When set to Vss, 32-bit bus mode is selected. In this mode, only SysAD(31:0) are part of the scan chain. When set to Vcc, 64-bit bus mode is selected. In this mode, SysAD(63:0) are part of the scan chain. This pin has a built-in pull-down device to guarantee 32-bit scan, if it is left uncovered.
JR_Vcc	I	JTAG VCC This pin has an internal pull-down to continuously reset the JTAG controller (if left unconnected) bypassing the TRst* pin. When supplied with Vcc, the TRst* pin will be the primary control for the JTAG reset.

Table 5 Pin Descriptions (Page 2 of 2)

Logic Diagram — RC64474/RC64475

Figure 2 illustrates the direction and functional groupings for the processor signals.

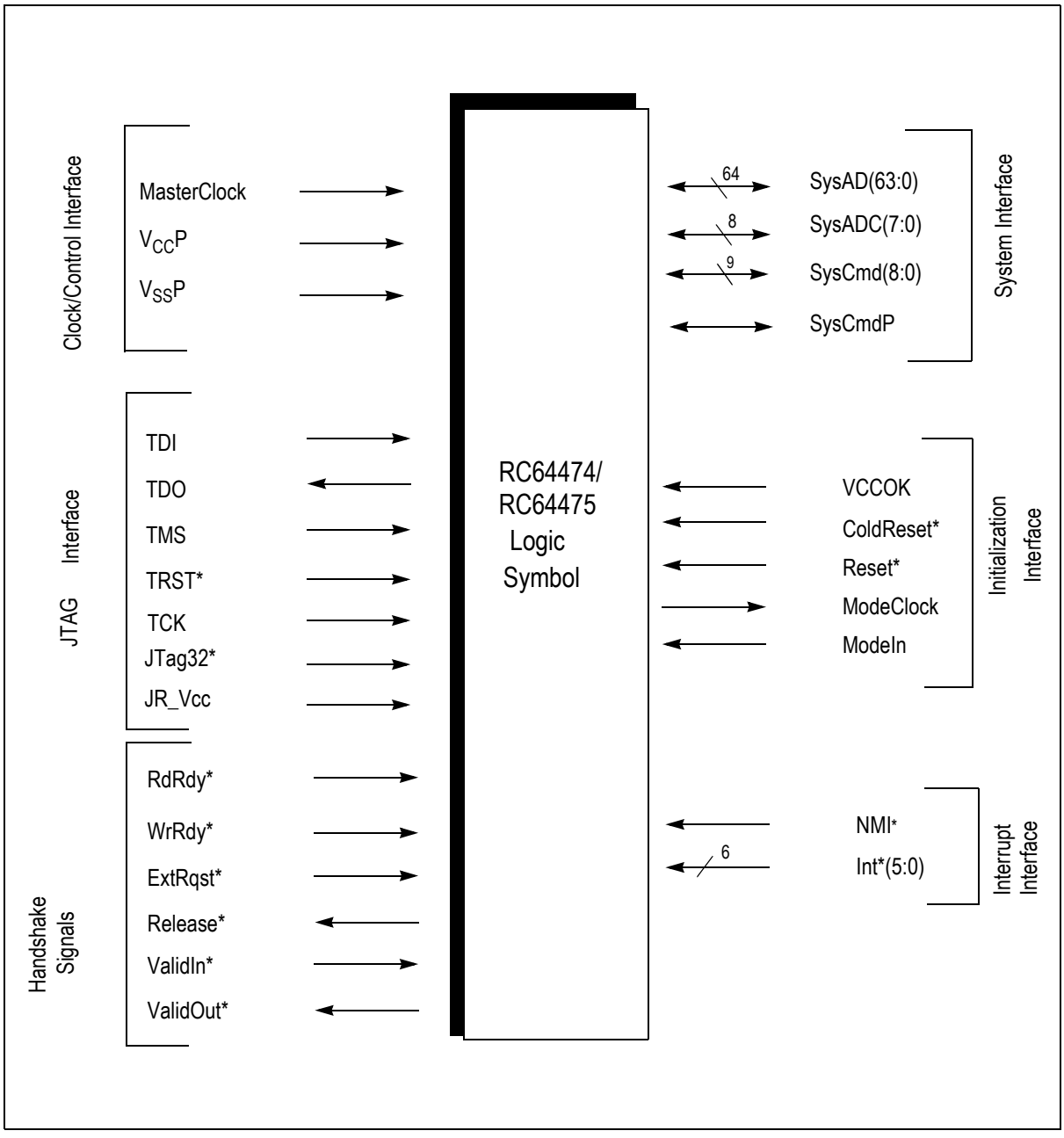


Figure 2 Logic Diagram for RC64474/RC64475

RC64475 208-pin QFP Package Pin-out

Pin names followed by an asterisk (*) are active when low. For maximum flexibility and compatibility with future designs, N.C. pins should be left floating.

Pin	Function	Pin	Function	Pin	Function	Pin	Function
1	N.C.	53	JTAG32*	105	N.C.	157	N.C.
2	N.C.	54	N.C.	106	N.C.	158	N.C.
3	N.C.	55	N.C.	107	N.C.	159	SysAD59
4	N.C.	56	N.C.	108	N.C.	160	ColdReset*
5	N.C.	57	SysCmd2	109	N.C.	161	SysAD28
6	N.C.	58	SysAD36	110	N.C.	162	VCC
7	N.C.	59	SysAD4	111	N.C.	163	V_{SS}
8	N.C.	60	SysCmd1	112	N.C.	164	SysAD60
9	N.C.	61	V_{SS}	113	N.C.	165	Reset*
10	SysAD11	62	V_{cc}	114	SysAD52	166	SysAD29
11	V_{SS}	63	SysAD35	115	ExtRqst*	167	SysAD61
12	V_{cc}	64	SysAD3	116	V_{cc}	168	SysAD30
13	SysCmd8	65	SysCmd0	117	V_{SS}	169	V_{cc}
14	SysAD42	66	SysAD34	118	SysAD21	170	V_{SS}
15	SysAD10	67	V_{SS}	119	SysAD53	171	SysAD62
16	SysCmd7	68	V_{cc}	120	RdRdy*	172	SysAD31
17	V_{SS}	69	SysAD2	121	Modein	173	SysAD63
18	V_{cc}	70	Int5*	122	SysAD22	174	V_{cc}
19	SysAD41	71	SysAD33	123	SysAD54	175	V_{SS}
20	SysAD9	72	SysAD1	124	V_{cc}	176	V_{cc}OK
21	SysCmd6	73	V_{SS}	125	V_{SS}	177	SysADC3
22	SysAD40	74	V_{cc}	126	Release*	178	SysADC7
23	V_{SS}	75	Int4*	127	SysAD23	179	N.C.
24	V_{cc}	76	SysAD32	128	SysAD55	180	TDI
25	SysAD8	77	SysAD0	129	NMI*	181	TRst*
26	SysCmd5	78	Int3*	130	V_{cc}	182	TCK
27	SysADC4	79	V_{SS}	131	V_{SS}	183	TMS
28	SysADC0	80	V_{cc}	132	SysADC2	184	TDO
29	V_{SS}	81	Int2*	133	SysADC6	185	V_{cc}P
30	V_{cc}	82	SysAD16	134	SysAD24	186	V_{SS}P
31	SysCmd4	83	SysAD48	135	V_{cc}	187	MasterClock
32	SysAD39	84	Int1*	136	V_{SS}	188	V_{cc}
33	SysAD7	85	V_{SS}	137	SysAD56	189	V_{SS}

Table 6 RC64475 208-pin QFP Package Pin-Out (Page 1 of 2)

Pin	Function	Pin	Function	Pin	Function	Pin	Function
14	Vcc	46	VssP	78	Vcc	110	Int2*
15	Vss	47	VccP	79	SysAD24	111	Vcc
16	SysAdC0	48	TDO	80	SysADC2	112	Vss
17	SysCmd5	49	TMS	81	Vss	113	Int3*
18	SysAD8	50	TCK	82	Vcc	114	SysAD0
19	Vcc	51	TRst*	83	NMI*	115	Int4*
20	Vss	52	TDI	84	SysAD23	116	Vcc
21	SysCmd6	53	Vss	85	Release*	117	Vss
22	SysAD9	54	SysADC3	86	Vss	118	SysAD1
23	Vcc	55	VccOK	87	Vcc	119	Int5*
24	Vss	56	Vss	88	SysAD22	120	SysAD2
25	SysCCmd7	57	Vcc	89	Modein	121	Vcc
26	SysAD10	58	SysAD31	90	RdRdy*	122	Vss
27	SysCmd8	59	Vss	91	SysAD21	123	SysCmd0
28	Vcc	60	Vcc	92	Vss	124	SysAd3
29	Vss	61	SysAD30	93	Vcc	125	Vcc
30	SysAD11	62	SysAD29	94	ExtRqst*	126	Vss
31	SysCmdP	63	Reset*	95	SysAD20	127	SysCmd1
32	SysAD12	64	Vss	96	ValidOut*	128	SysAD4

Table 7 RC64474 128-pin QFP Package Pin-out (Page 2 of 2)

Socket Compatibility—RC64474 & RC4640

To ensure socket compatibility between the RC4640 and the RC64474 devices, several pin changes are required, as shown below.

Pin	RC4640	RC64574/ RC64474	Compatible to RV4640?	Comments
1	N.C	JTAG32*	Yes.	Pin has an internal pull-down, to enable 32-bit scan. Can also be left a N.C.
48	V_{ss}	TDO	Yes.	Can be driven with V_{ss}, if JTAG is not needed. Is tristated when TRst* is low.
49	V_{ss}	TMS	Yes.	Can be driven with V_{ss} if JTAG is not needed.
50	V_{ss}	TCK	Yes.	Can be driven with V_{ss} if JTAG is not needed.
51	V_{ss}	TRst*	Yes.	Can be driven with V_{ss} if JTAG is not needed.
52	V_{ss}	TDI	Yes.	Can be driven with V_{ss} if JTAG is not needed.
71	N.C.	JR_V_{cc}	Yes.	Can be left N.C. in RC64474, if JTAG is not need. If JTAG is needed, it must be driven to V_{cc}.

Table 8 RC64574 Socket Compatibility to RC64474 and R4640

Socket Compatibility—RC64475 & RC4650

Pin	RV4650 32-bit	RC64575 32-bit RC64475 32-bit	RV4650 64-bit	RC64575 64-bit RC64475 64-bit	Compatible to RV4650?	Comments
53	N.C.	JTAG32*	No Connect	JTAG32*	Yes	In 32-bit, this pin can be left unconnected because of internal pull-down. In 64-bit, this assumes that JTAG will not be used. If using JTAG, this pin must be at V_{cc}.
150	N.C.	JR_V_{cc}	No Connect	JR_V_{cc}	Yes	In RC64475, can be left a N.C, if JTAG is not need. If JTAG is needed, it must be driven to V_{cc}.
180	N.C.	TDI	No Connect	TDO	Yes	If JTAG is not needed, can be left a N.C.
181	N.C.	TRsT*	No Connect	TRsT*	Yes	If JTAG is not needed, can be left a N.C.
182	N.C.	TCK	No Connect	TCK	Yes	If JTAG is not needed, can be left a N.C.
183	N.C.	TMS	No Connect	TMS	Yes	If JTAG is not needed, can be left a N.C.
184	N.C.	TDO	No Connect	TDIO	Yes	If JTAG is not needed, can be left a N.C.

Table 9 RC64575 Socket Compatibility to RC64475 & RC4650

Absolute Maximum Ratings

Note: Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Symbol	Rating	RC64474/475 3.3V±5%	RC64474/475 3.3V±5%	Unit
		Commercial	Industrial	
V_{TERM}	Terminal Voltage with respect to GND	–0.5[1] to +4.6	–0.5[1] to +4.6	V
T_C	Operating Temperature(case)	0 to +85	-40 to +85	°C
T_{BIAS}	Case Temperature Under Bias	–55 to +125	–55 to +125	°C
T_{STG}	Storage Temperature	–55 to +125	–55 to +125	°C
I_{IN}	DC Input Current	20[2]	20[2]	mA
I_{OUT}	DC Output Current	50[3]	50[3]	mA

1. V_{IN} minimum = –2.0V for pulse width less than 15ns. V_{IN} should not exceed V_{CC} +0.5 Volts.
2. When V_{IN} < 0V or V_{IN} > V_{CC}
3. Not more than one output should be shorted at a time. Duration of the short should not exceed 30 seconds.

Recommended Operation Temperature and Supply Voltage

Grade	Temperature	Gnd	RC64474/475
			V_{cc}
Commercial	0°C to +85°C (Case)	0V	3.3V±5%
Industrial	-40 + 85°C (Case)	0V	3.3V±5%

DC Electrical Characteristics

Commercial Temperature Range—RC64474/64475

(V_{CC} = 3.3±5%, T_{CASE} = 0°C to +85°C)

Parameter	RC64474/RC64475 180MHz		RC64474/RC64475 200MHz		RC64474/RC64475 250MHz		Conditions
	Minimum	Maximum	Minimum	Maximum	Minimum	Maximum	
V_{OL}	—	0.1V	—	0.1V	—	0.1V	$\|I_{OUT}\|$= 20uA
V_{OH}	V_{CC} - 0.1V	—	V_{CC} - 0.1V	—	V_{CC} - 0.1V	—	
V_{OL}	—	0.4V	—	0.4V	—	0.4V	$\|I_{OUT}\|$= 4mA
V_{OH}	2.4V	—	2.4V	—	2.4V	—	
V_{IL}	–0.5V	$0.2V_{CC}$	–0.5V	$0.2V_{CC}$	–0.5V	$0.2V_{CC}$	—
V_{IH}	2.0V	V_{CC} + 0.5V	$0.7V_{CC}$	V_{CC} + 0.5V	2.0V	V_{CC} + 0.5V	—
I_{IN}	—	±10uA	—	±10uA	—	±10uA	$0 \le V_{IN} \le V_{CC}$
C_{IN}	—	10pF	—	10pF	—	10pF	—
C_{OUT}	—	10pF	—	10pF	—	10pF	—
I/O_{LEAK}	—	20uA	—	20uA	—	20uA	Input/Output Leakage

Power Consumption—RC64474

.

Parameter		RC64474 180MHz		RC64474 200MHz		RC64474 250MHz		Conditions
		Typical[1]	Max	Typical[1]	Max	Typical[1]	Max	
System Condition:		180/90MHz		200/100MHz		250/125MHz		—
I_{CC}	standby	—	60 mA[2]	—	60 mA[2]	—	100 mA[2]	C_L = 0pF[3]
		—	110 mA[2]	—	110 mA[2]	—	110 mA[2]	C_L = 50pF
	active	530 mA[2]	630 mA[2]	600mA[2]	700 mA[2]	700 mA[2]	850mA[2]	C_L = 0pF No SysAd activity[3]
		630mA[2]	750 mA[2]	700 mA[2]	850 mA[2]	850mA[2]	1000mA[2]	C_L = 50pF R4x00 compatible writes, T_C = 25°C
		750 mA[2]	1050 mA[4]	850 mA[2]	1200 mA[4]	1000mA[2]	1400mA[2]	C_L = 50pF Pipelined writes or write re-issue, T_C = 25°C[3]

1. Typical integer instruction mix and cache miss rates
2. These are not tested. They are the results of engineering analysis and are provided for reference only
3. Guaranteed by design.
4. These are the specifications IDT tests to insure compliance.

Power Consumption—RC64475

Parameter		RC64475 180MHz		RC64475 200MHz		RC64475 250MHz		Conditions
		Typical[1]	Max	Typical[1]	Max	Typical[1]	Max	
System Condition:		180/90MHz		200/100MHz		250/125MHz		—
I_{CC}	standby	—	60 mA[2]	—	60 mA[2]	—	100 mA[2]	C_L = 0pF[3]
		—	110 m^2A	—	110 mA[2]	—	110 mA[2]	C_L = 50pF
	active, 64-bit bus option[4]	720 mA[2]	850 mA[2]	850 mA[2]	1000 mA[2]	935 mA[2]	1100 mA[2]	C_L = 0pF No SysAd activity[3]
		850 mA[2]	1000 mA[2]	1000 mA[2]	1200 mA[2]	1100mA[2]	1360mA[2]	C_L = 50pF R4x00 compatible writes, T_C = 25°C
		1000 mA[2]	1200 mA[5]	1200 mA[2]	1400 mA[5]	1360 mA[2]	1600 mA[2]	C_L = 50pF Pipelined writes or write re-issue, T_C = 25°C[3]

1. Typical integer instruction mix and cache miss rates
2. These are not tested. They are the results of engineering analysis and are provided for reference only.
3. Guaranteed by design.
4. In 32-bit bus option, use RC64474 power consumption values.
5. These are the specifications IDT tests to insure compliance.

Timing Characteristics—RC64474/RC64475

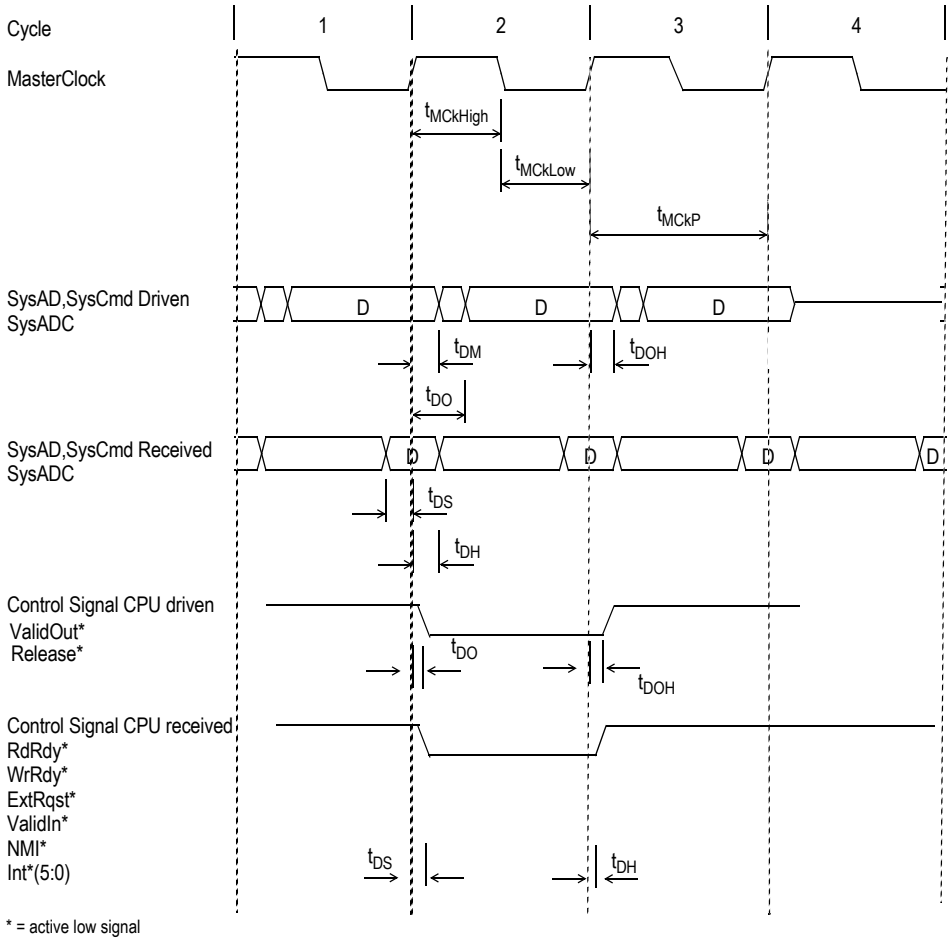


Figure 3 System Clocks Data Setup, Output, and Hold Timing

Capacitive Load Deration—RC64474/RC64475

Parameter	Symbol	Test Conditions	180MHz		200MHz†		250MHz†		Units
			Min	Max	Min	Max	Min	Max	
Load Derate	C_{LD}	—	—	2	—	2	—	2	ns/25pF

System Interface Parameters

Note: Operation of the RC64474/RC64475 is only guaranteed with the Phase Lock Loop enabled.

Parameter[1]	Symbol	Test Conditions	RC64474/ RC64475 180MHz		RC64474/ RC64475 200MHz		RC64474/ RC64475 250MHz		Units
			Min	Max	Min	Max	Min	Max	
Data Output[2]	t_{DM}= Min t_{DO} = Max	$mode_{14..13}$ = 10	0[3]	6	0[3]	5	0[3]	4.7	ns
		$mode_{14..13}$ = 11	0[3]	6	0[3]	5	0[3]	4.7	ns
		$mode_{14..13}$ = 00	—	9	—	9	—	7	ns
		$mode_{14..13}$ = 01	—	9	—	9	—	7	ns
Data Output Hold	t_{DOH}[4]	$mode_{14..13}$ = 10	0[3]	—	0[3]	—	0[3]	—	ns
		$mode_{14..13}$ = 11	0[3]	—	0[3]	—	0[3]	—	ns
		$mode_{14..13}$ = 00	0[3]	—	0[3]	—	0[3]	—	ns
		$mode_{14..13}$ = 01	0[3]	—	0[3]	—	0[3]	—	ns
Input Data Setup	t_{DS}	t_{rise} = 5ns t_{fall} = 5ns	2	—	2	—	2	—	ns
Input Data Hold	t_{DH}		1.0	—	1.0	—	1.0	—	ns

1. Timings are measured from 1.5V of the clock to 1.5V of the signal.
2. Capacitive load for all output timings is 50pF.
3. Guaranteed by design.
4. 50pf loading on external output signals, fastest settings. Also applies to JTAG signals (TRST*,TDO,TDI,TMS)

Boot-Time Interface Parameters

Parameter	Symbol	RC64474/ RC64475 180 MHz		RC64474/ RC64475 200 MHz		RC64474/ RC64475 250MHz		Units
		Min	Max	Min	Max	Min	Max	
Mode Data Setup	t_{DS}	3	—	3	—	3	—	Master Clock Cycle
Mode Data Hold	t_{DH}	0	—	0	—	0	—	Master Clock Cycle

Mode Configuration Interface Reset Sequence

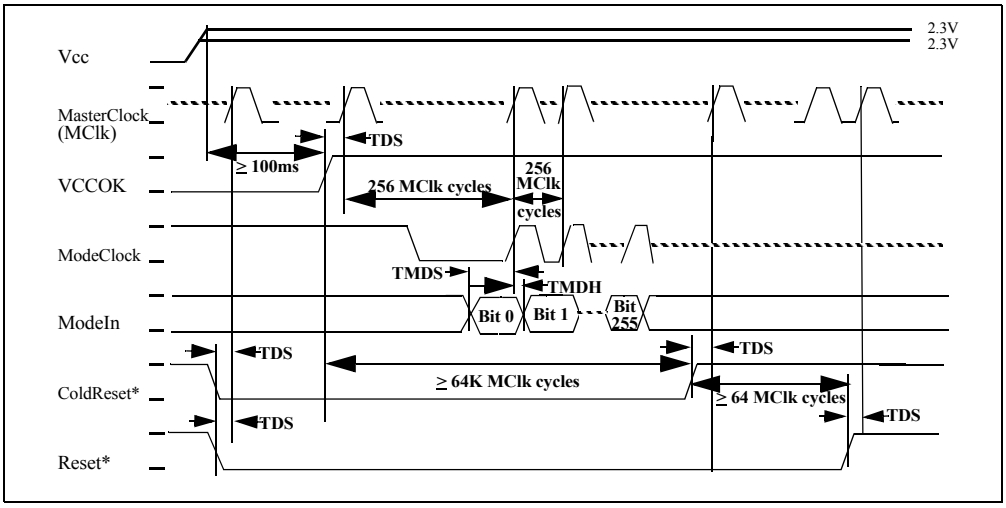


Figure 5 Power-on Reset

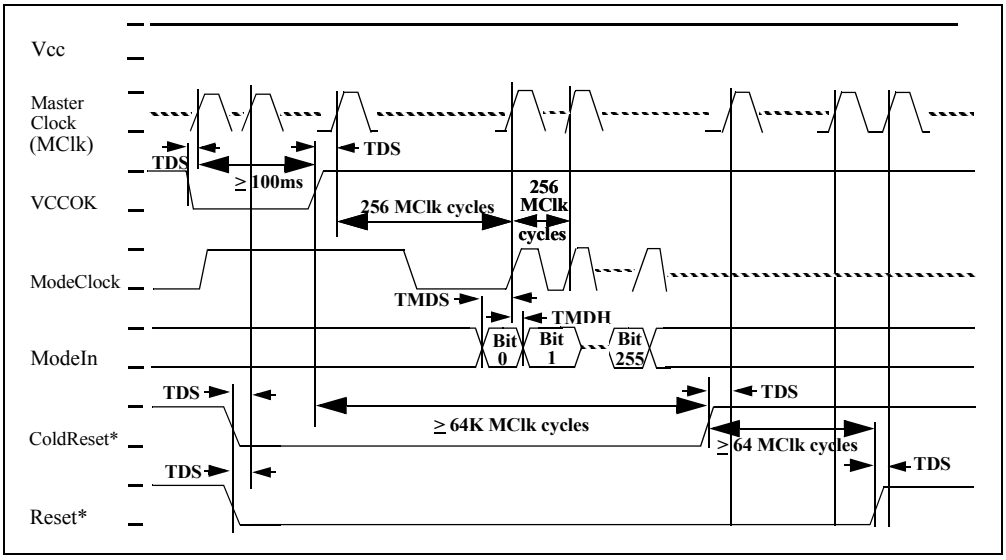


Figure 6 Cold Reset

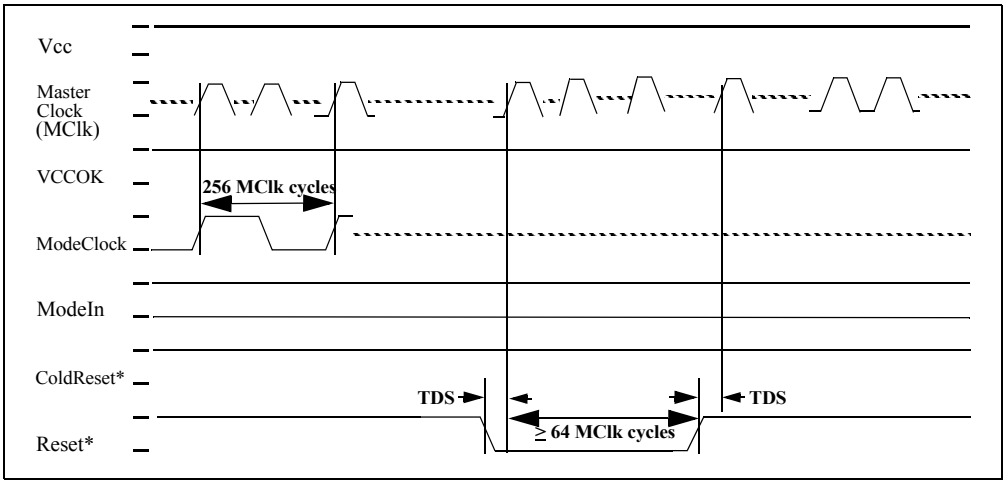
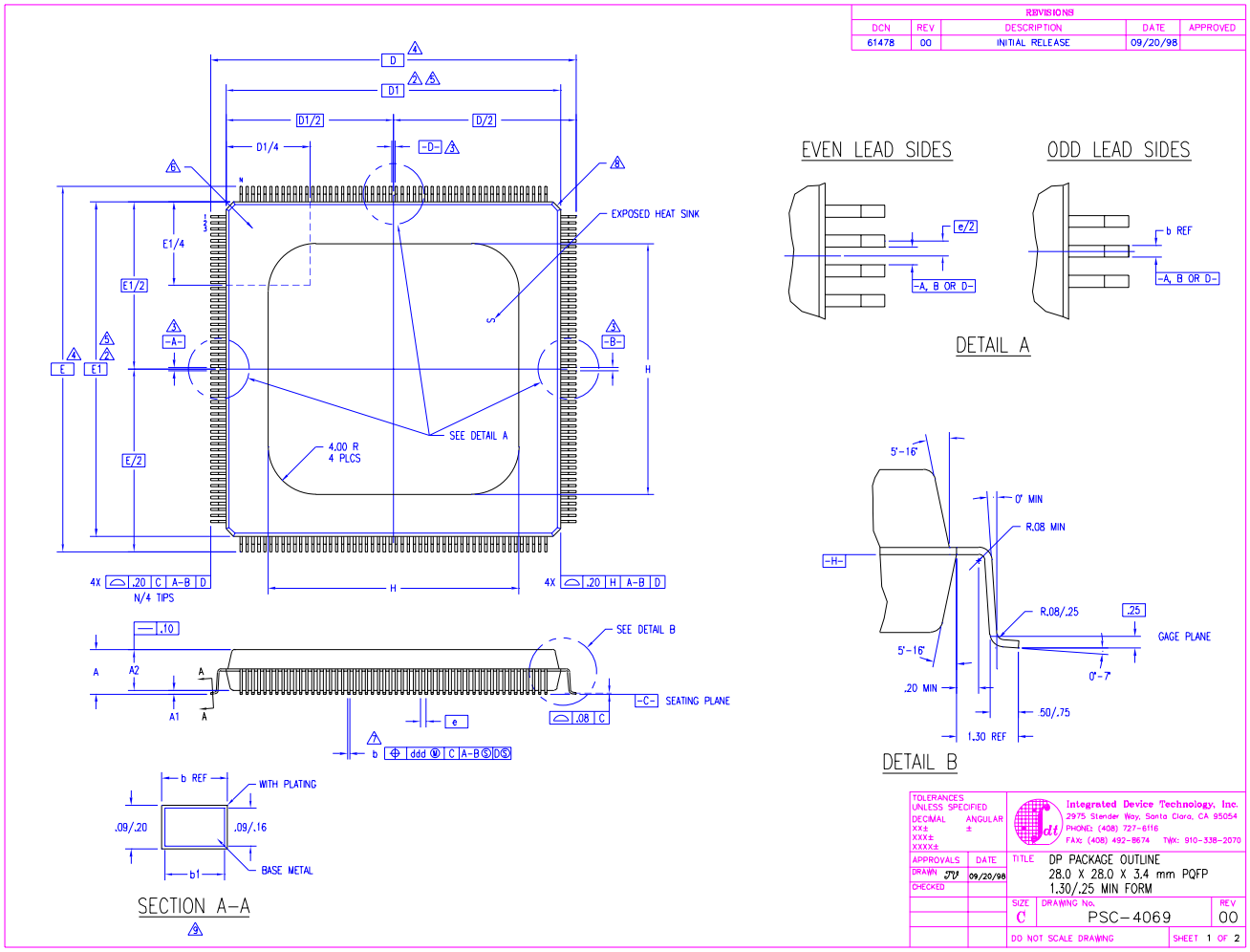


Figure 7 Warm Reset

RC64475 Physical Specifications

The RC64475 is available in a 208-pin power quad (PQUAD) package.



RC64475 208-pin Package (page 2)

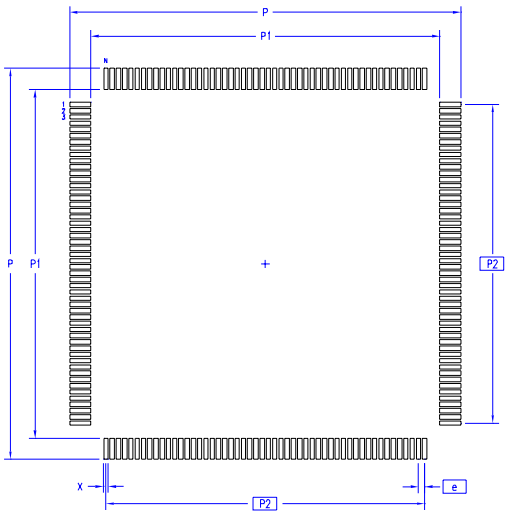
REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
61478	00	INITIAL RELEASE	09/20/98	

SYMBOL	JEDEC VARIATION FA-1 MIN	NOM	MAX	NOTE
A	–	–	4.10	
A1	.25	–	–	
A2	3.20	3.40	3.60	
D	30.60 BSC			4
D1	28.00 BSC			5,2
E	30.60 BSC			4
E1	28.00 BSC			5,2
H	21.00 REF			
N	208			
e	.50 BSC			
b	.17	–	.27	7
b1	.17	.20	.23	
ddd	–	–	.08	

NOTES:

1. ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994
2. TOP PACKAGE MAY BE SMALLER THAN BOTTOM PACKAGE BY .15 mm
3. DATUMS [A-B] AND [-D-] TO BE DETERMINED AT DATUM PLANE [-H-]
4. DIMENSIONS D AND E ARE TO BE DETERMINED AT SEATING PLANE [-C-]
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS .25 mm PER SIDE. D1 AND E1 ARE BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH
6. DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
7. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
10. ALL DIMENSIONS ARE IN MILLIMETERS
11. THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-143, VARIATION FA-1

LAND PATTERN DIMENSIONS



	MIN	MAX
P	31.20	31.40
P1	27.80	28.00
P2	25.50 BSC	
X	.30	.40
e	.50 BSC	
N	208	

TOLERANCES UNLESS SPECIFIED
DECIMAL ANGULAR
XX± ±
XXX±
XXXX±

APPROVALS DATE
DRAWN JTV 09/20/98
CHECKED

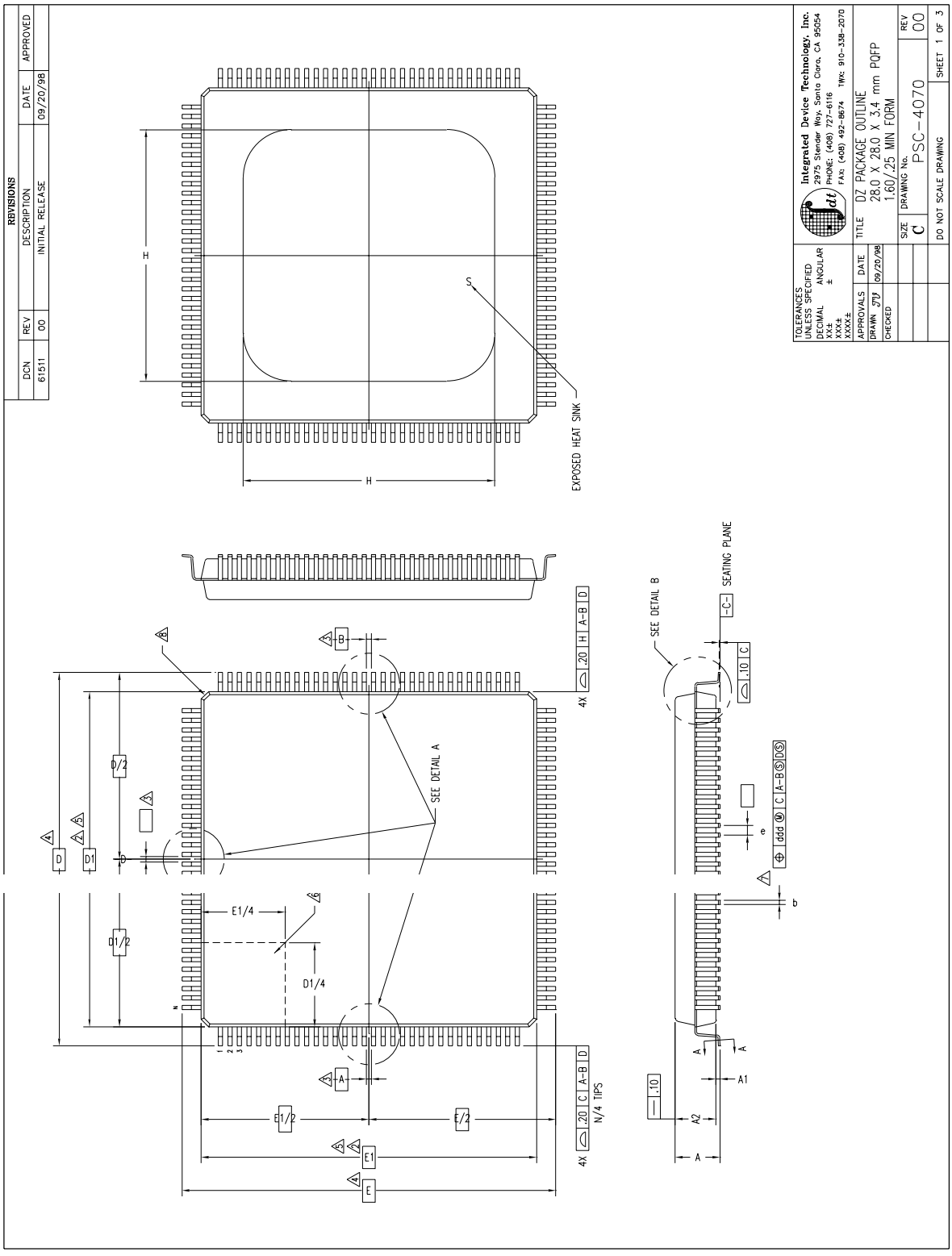
Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA 95054
PHONE: (408) 727-6116
FAX: (408) 492-8674 TWX: 910-338-2070

TITLE: DP PACKAGE OUTLINE
28.0 X 28.0 X 3.4 mm PQFP
1.30/.25 MIN FORM

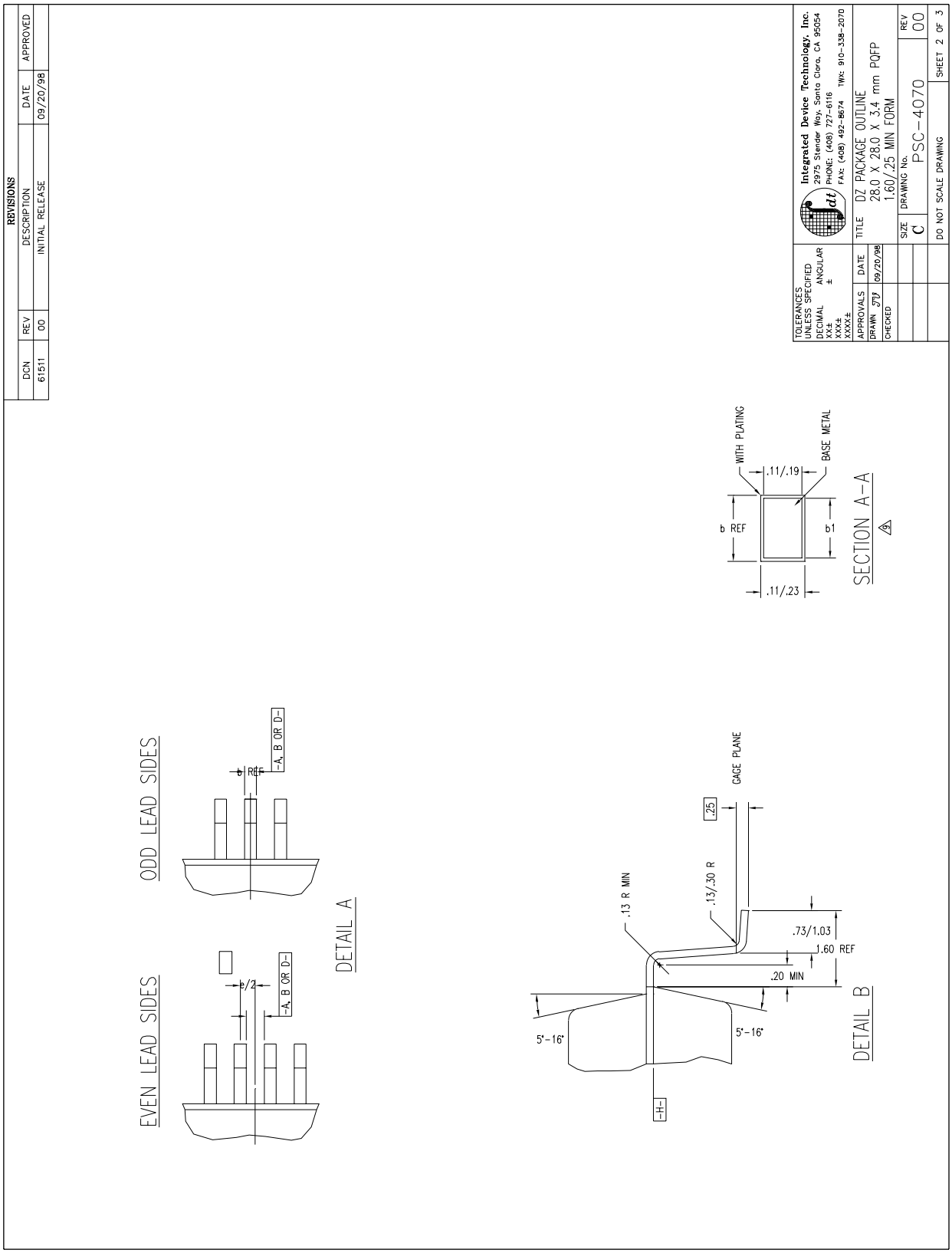
SIZE C | DRAWING No. PSC-4069 | REV 00

DO NOT SCALE DRAWING | SHEET 2 OF 2

RC64474 128-Pin Package (Page 1 of 3)



RC64474 128-pin Package (page 2 of 3)



REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
61511	00	INITIAL RELEASE	09/20/98	

SYMBOL	JEDEC VARIATION DB-1			NOTE
	MIN	NOM	MAX	
A	–	–	4.10	
A1	.25	–	–	
A2	3.20	3.40	3.60	
D	31.20 BSC			4
D1	28.00 BSC			5,2
E	31.20 BSC			4
E1	28.00 BSC			5,2
H	21.00 REF			
N	128			
e	.80 BSC			
b	.29	–	.45	7
b1	.29	.35	.41	
ddd	–	–	.20	

NOTES:

1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M–1994

2 TOP PACKAGE MAY BE SMALLER THAN BOTTOM PACKAGE BY .15 mm

3 DATUMS A-B AND -D- TO BE DETERMINED AT DATUM PLANE -H-

4 DIMENSIONS D AND E ARE TO BE DETERMINED AT SEATING PLANE -C-

5 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS .25 mm PER SIDE. D1 AND E1 ARE BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH

6 DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED

7 DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.

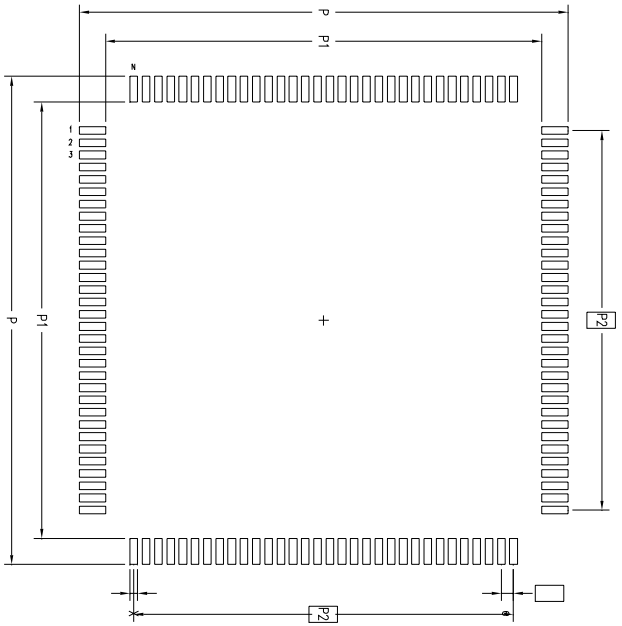
8 EXACT SHAPE OF EACH CORNER IS OPTIONAL

9 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP

10 ALL DIMENSIONS ARE IN MILLIMETERS

11 THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MS-022, VARIATION DB-1

LAND PATTERN DIMENSIONS



	MIN	MAX
P	31.80	32.00
P1	28.40	28.60
P2	24.80 BSC	
X	.40	.60
e	.80 BSC	
N	128	

TOLERANCES UNLESS SPECIFIED
DECIMAL ANGULAR
XX± ±
XXX±
XXXX±

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2975 Stender Way, Santa Clara, CA 95054
PHONE: (408) 727-6116
FAX: (408) 492-8674 TWX: 910-338-2070

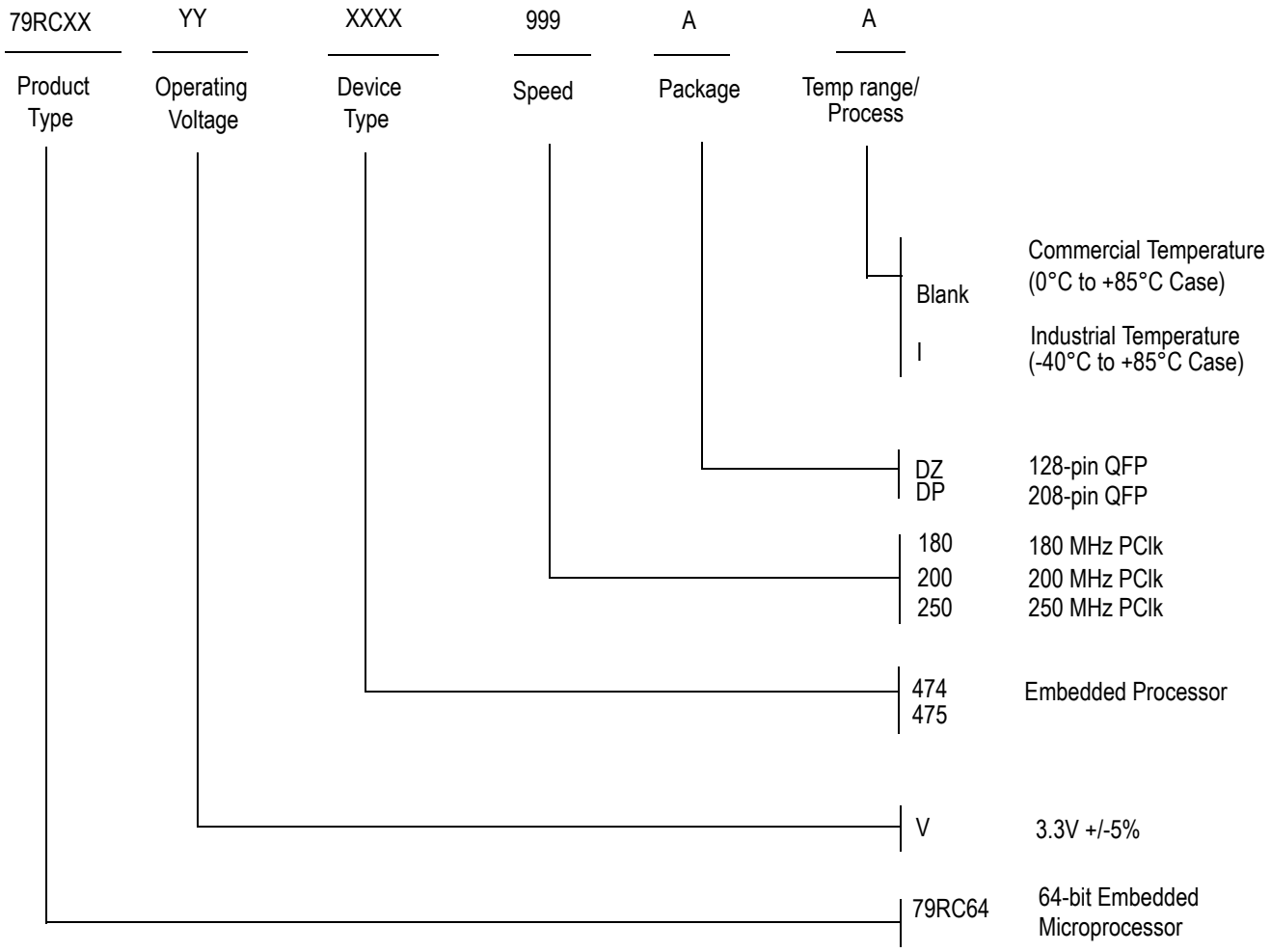
APPROVALS	DATE
DRAWN JTV	09/20/98
CHECKED	

TITLE DZ PACKAGE OUTLINE
28.0 X 28.0 X 3.4 mm PQFP
1.60/.25 MIN FORM

SIZE C | DRAWING No. PSC-4070 | REV 00

DO NOT SCALE DRAWING | SHEET 3 OF 3

Ordering Information



Valid Combinations

79RC64V474 - 180, 200, 250 DZ	128-pin QFP package, Commercial Temperature
79RC64V475 - 180, 200, 250 DP	208-pin QFP package, Commercial Temperature
79RC64V474 - 180, 200, 250 DZI	128-pin QFP package, Industrial Temperature
79RC64V475 - 180, 200, 250 DPI	208-pin QFP package, Industrial Temperature

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